

## Set-Cast 13254

### Low Viscosity Filled Epoxy Compound

**Set-Cast 13254** is a low viscosity, filled epoxy formulation which is used for encapsulation and embedment of electronic components. **Set-Cast 13254** has excellent electrical properties and exceptional adhesion to most substrates. **Set-Cast 13254** is 100% solids.

**PROPERTIES - UNCURED:**

	<b><u>Part A</u></b>	<b><u>Part B (PC 67)</u></b>	
Color, Visual	Blue/Silver/Black	Brown	
Viscosity, cps.	6,000	900	ASTMD2393
Specific Gravity	1.50	1.0	
Mix Ratio (By Weight)		100:18	
Mixed Viscosity, cps.		4,500	ASTMD2393
Pot Life @ 72° F, min.		35	
Shelf Life @ 72° F, months		6	

**PROPERTIES - CURED:**

**PHYSICAL**

Hardness Durometer (Shore D)		81	ASTMD 2240
Tensile Strength, psi		8000	ASTMD 638
Compressive Strength, psi		13,500	ASTMD 695
Flexural Strength, psi		13,500	ASTMD 790
Coefficient of Thermal Expansion (cm/cm/°C)		9 x 10 <sup>-6</sup>	
Service Temperature		260°F	
Dielectric Strength, volts/mil		480	ASTMD 149
Volume Resistivity, ohm-cm		5 x 10 <sup>16</sup>	ASTMD 257
Thermal Conductivity, (BTU/in / ft <sup>2</sup> F).....	5		

**MIXING INSTRUCTIONS:**

1. Premix Set-Cast 13254 in the original container prior to use to ensure any settled filler may be reincorporated. Warming Set-Cast 13254 to 100°F facilitates ease of use.
2. Weigh out the required amount of Set-Cast 13254 Part A and the requisite Part B.
3. Mix thoroughly, scraping both sides and bottom of container.
4. Evacuate mixture at 29 in. Hg for 5-10 minutes (if desired).
5. Pour into mold or cavity.

**CURE SCHEDULE:**

Overnight at Room temp. (75°F)

## **Warranty**

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